

# RYR9000 Series

## Hardware Design Guide



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## APPLICABILITY TABLE

PRODUCTS
RYP91NA
RYP91NS
RYP91AP
RYP91EU
RYP91EX
RYP91NF
RYP91LA
RYP91WX
RYP91NA_UART
RYP91NS_UART
RYP91AP_UART
RYP91EU_UART
RYP91EX_UART
RYP91NF_UART
RYP91LA_UART
RYP91WX_UART

## 1. PINS ALLOCATION

### 1.1 Pin-out

Pin	Signal	I/O	Function	Type	Comment
Power Supply					
2	VCC	-	3.3V Main Power Supply	Power	
24	VCC	-	3.3V Main Power Supply	Power	
39	VCC	-	3.3V Main Power Supply	Power	
41	VCC	-	3.3V Main Power Supply	Power	
52	VCC	-	3.3V Main Power Supply	Power	
4	GND	-	Ground		
9	GND	-	Ground		
15	GND	-	Ground		
18	GND	-	Ground		
21	GND	-	Ground		
26	GND	-	Ground		
27	GND	-	Ground		
29	GND	-	Ground		
34	GND	-	Ground		
35	GND	-	Ground		
37	GND	-	Ground		
40	GND	-	Ground		
43	GND	-	Ground		
50	GND	-	Ground		
USB Interface (Standard Version only)					
36	USB D-	I/O	USB differential Data (-)		
38	USB D+	I/O	USB differential Data (+)		
SIM Card Interface					
8	SIMVCC	I/O	External SIM signal – Power supply for the SIM	1.8 / 3V	
10	SIMIO	I/O	External SIM signal - Data I/O	1.8 / 3V	
12	SIMCLK	O	External SIM signal – Clock	1.8 / 3V	
14	SIMRST	O	External SIM signal – Reset	1.8 / 3V	

Pin	Signal	I/O	Function	Type	Comment
UART Interface (UART Version only)					
23	TXD	I	Serial data input (TXD) from DTE	1.8V	
25	CTS	O	Output for Clear to send signal (CTS) to DTE	1.8V	
28	RTS	O	Input for Request to send signal (RTS) from DTE	1.8V	See note below
30	DCD	I	Output for Data Carrier Detect (DCD) to DTE	1.8V	
31	RXD	O	Serial data output to DTE	1.8V	
44	RING	O	Output for Ring Indication (RI) to DTE	1.8V	
46	DTR	I	Input for Data Terminal Ready (DTR) from DTE	1.8V	
48	DSR	O	Output for Data Set Ready (DSR) to DTE	1.8V	
Miscellaneous Functions					
6	VREG_MSME	O	The pin is always HI while RYP9000 is working	1.8V	
22	RESET	I	Active low functional reset input to the card	1.8V	
42	STATUS_LED	O	Status indicator LED, Open drain output.	1.8V	
Reserved					
1	Reserved	-			
3	Reserved	-			
5	Reserved	-			
7	Reserved	-			
11	Reserved	-			
13	Reserved	-			
16	Reserved	-			
17	Reserved	-			
19	Reserved	-			
20	Reserved	-			
32	Reserved	-			

Reserved					
33	Reserved	-			
45	Reserved	-			
47	Reserved	-			
49	Reserved	-			
51	Reserved	-			



**Note:** When the UART signals are used as the communication port between the host and the modem, the RTS must be connected to GND (on the module side) if flow control is not used.  
If the UART port is not used, all UART signals can be left disconnected.



**Note:** Unless otherwise specified, RESERVED pins must be left unconnected (floating).

## 2. POWER SUPPLY

The power supply circuitry and board layout are a very important part in the complete product design and they strongly reflect on the overall performance of the product, so please read carefully the requirements and the guidelines that will follow for a proper design.

### 2.1. Power Supply Requirements

The external power supply must be connected to VBATT signal and must fulfil the following requirements:

Power Supply	Value
Nominal Supply Voltage	3.3V
Supply Voltage Range	3 ~ 5.5V
Max ripple on module input supply	30mV



**Note:** The Operating Voltage Range MUST never be exceeded; care must be taken when designing the power section of the application to avoid having an excessive voltage drop.

If the voltage drop exceeds the limits, it could cause the module to Power Off.

The overshoot voltage (regarding MAX Extended Operating Voltage) and drop in voltage (regarding MIN Extended Operating Voltage) MUST never be exceeded;

The “Extended Operating Voltage Range” can only be used with the complete assumption and application of the HW User guide suggestions.

### 2.2. Electrical Design Guidelines

The electrical design of the power supply strongly depends on the power source where this power is drained.

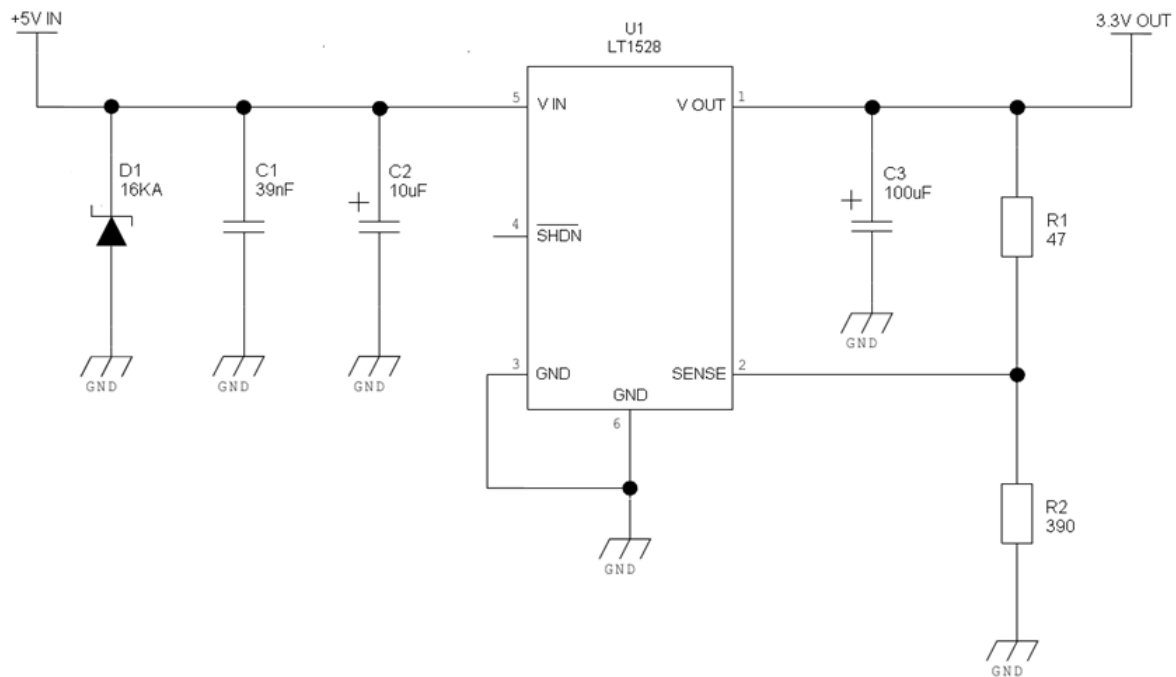
- +5V input (typically PC internal regulator output)
- +12V input (typically automotive)

#### 2.2.1 +5V Source Power Supply Design Guidelines

- The desired output for the power supply is 3.3V, so there's not a big difference between the input source and the desired output and a linear regulator can be used. A switching power supply will not be suitable because of the low drop out requirements.

- When using a linear regulator, a proper heat sink shall be provided in order to dissipate the generated heat.
- A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks close to the Module, a 100 $\mu$ F capacitor is usually suitable.
- Make sure the low ESR capacitor on the power supply output rated at least 10V.

An example of linear regulator with 5V input is:

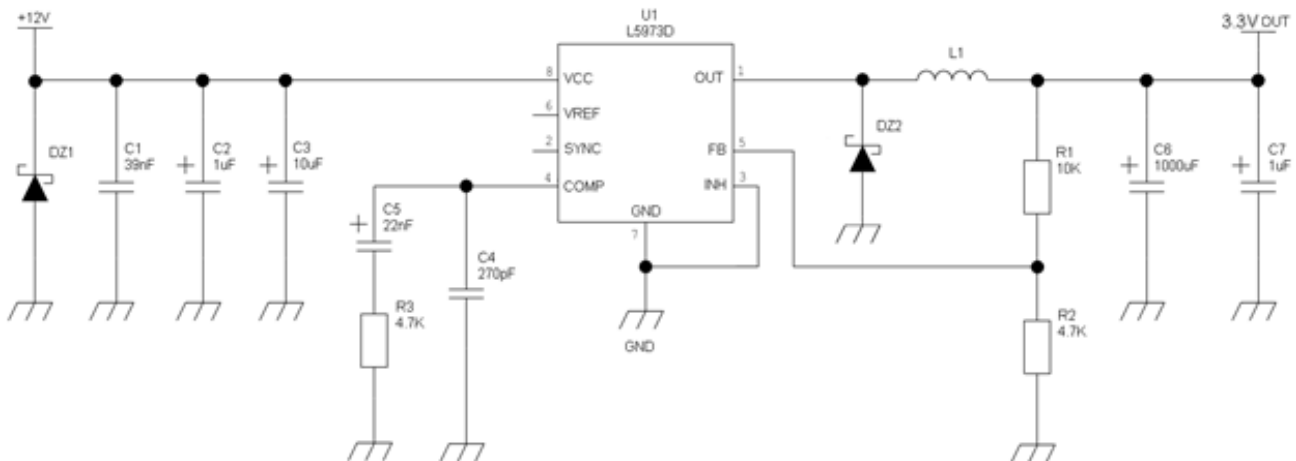


### 2.2.2 +12V Source Power Supply Design Guidelines

- The desired output for the power supply is 3.3V, so due to the big difference between the input source and the desired output, a linear regulator is not suitable and shall not be used. A switching power supply will be preferable because of its better efficiency.
- When using a switching regulator, a 500kHz or more switching frequency regulator is preferable because of its smaller inductor size and its faster transient response. This allows the regulator to respond quickly to the current peaks absorption.
- In any case the frequency and Switching design selection is related to the application to be developed since the switching frequency could also generate EMC interferences.
- For car PB battery the input voltage can rise up to 15,8V and this should be kept in mind when choosing components: all components in the power supply must withstand this voltage.
- A Bypass low ESR capacitor of adequate capacity must be provided in order to cut the current absorption peaks, a 100 $\mu$ F capacitor is usually suitable.
- Make sure the low ESR capacitor on the power supply output is rated at least 10V.
- For Car applications, a spike protection diode should be inserted close to the power input, in order to clean the supply from the spikes.



An example of switching regulator with 12V input is in the below schematic:



## 2.3. Thermal Design Guidelines

The thermal design of the application board and the power supply heat sink should be done with the following specifications:

- Typical average current consumption during R9R9000\_Series Mini PCIe transmission @ Max PWR level at min battery level (LTE) : 700 mA
- Average current during idle (USB enabled): 30 mA
- Average current during idle (USB disabled): 5 mA
- Average current during airplane mode (USB disabled): 2 mA

Considering the very low current during Idle, especially if the Power Saving function is enabled, it is possible to consider from the thermal point of view that the device absorbs significant current mainly during the Data session. In LTE/WCDMA/HSPA mode, the R9R9000\_Series Mini PCIe emits RF signals continuously during transmission. Therefore, special attention must be paid to how to dissipate the heat generated.

## 2.4. Power Supply PCB Layout Guidelines

The GSM system is made in a way that the RF transmission is not continuous, otherwise it is packed into bursts at a base frequency of about 216 Hz, and the relative current peaks can be as high as about 2.4A. Therefore the power supply must be designed in such a way to withstand with these current peaks without large voltage drops; this means that both the electrical design and the board layout must be designed for this current flow. If the voltage drop during the peak current absorption is too much, then the device may even shutdown as a consequence of the drop in the supply voltage.



**Note:** The electrical design for the Power supply should be made ensuring it will be capable of a peak current output of at least 2.4 A.

As seen on the electrical design guidelines, the power supply shall have a low ESR

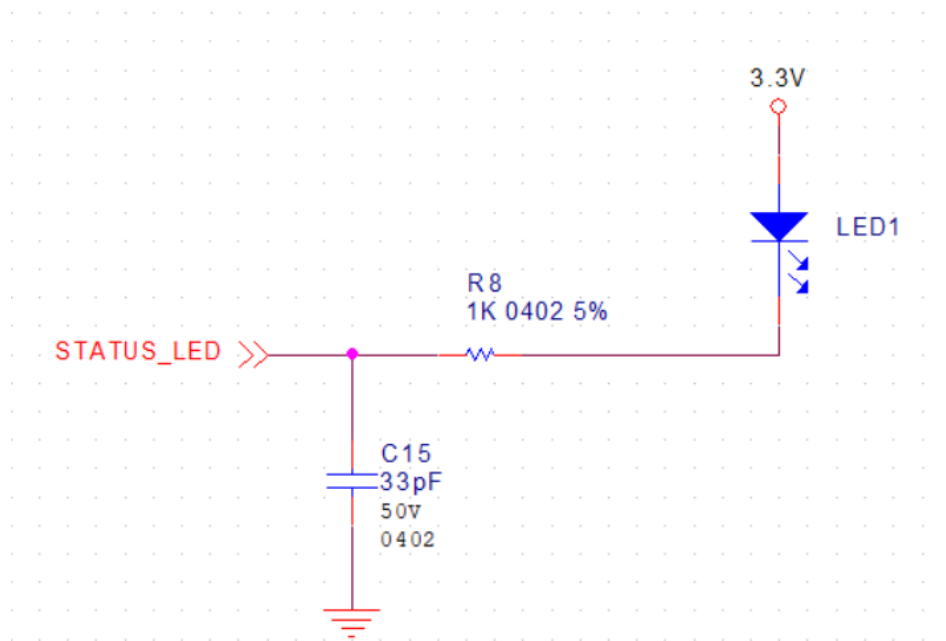
capacitor on the output to cut the current peaks on the input to protect the supply from spikes. The placement of this component is crucial for the correct working of the circuitry. A misplaced component can be useless or can even decrease the performance of the power supply.

- The Bypass low ESR capacitor must be placed close to the RYP9000\_Series -mPCIe power input pads or if the power supply is of the switching type it can be placed near the inductor to cut the ripple provided the PCB trace from the capacitor to the RYP9000\_Series -mPCIe is wide enough to ensure a dropless connection even during an 1A current peak.
- The protection diode must be placed close to the input connector where the power source is drained.
- The PCB traces from the input connector to the power regulator IC must be wide enough to ensure no voltage drops occur when a 1A current peak is absorbed.
- The PCB traces to the RYP9000\_Series -mPCIe and the Bypass capacitor must be wide enough to ensure that no significant voltage drops occur. This is for the same reason as previous point. Try to keep this trace as short as possible.
- To reduce the EMI due to switching, it is important to keep the mesh involved very small; therefore the input capacitor, the output diode (if not embodied in the IC) and the regulator have to form a very small loop. This is done in order to reduce the radiated field (noise) at the switching frequency (100-500 kHz usually).
- A dedicated ground for the Switching regulator separated by the common ground plane is suggested.
- The placement of the power supply on the board should be done in such a way to guarantee that the high current return paths in the ground plane are not overlapped to any noise sensitive circuitry as the microphone amplifier/buffer or earphone amplifier.
- The power supply input cables should be kept separate from noise sensitive lines such as microphone/earphone cables.
- The insertion of EMI filter on VBATT pins is suggested in those designs where antenna is placed close to battery or supply lines.
- A ferrite bead like Murata BLM18EG101TN1 or Taiyo Yuden P/N FBMH1608HM101 can be used for this purpose.

### 3. DIGITAL SECTION

#### 3.1. STATUS\_LED

STATUS\_LED is driven, by default, by the module according to the PCI Express Mini Card Electromechanical Specification Revision 2.1. If desired, LED behavior can be configured by adjusting the software settings. The following picture shows the internal STATUS\_LED driver and the recommended connection to a LED:

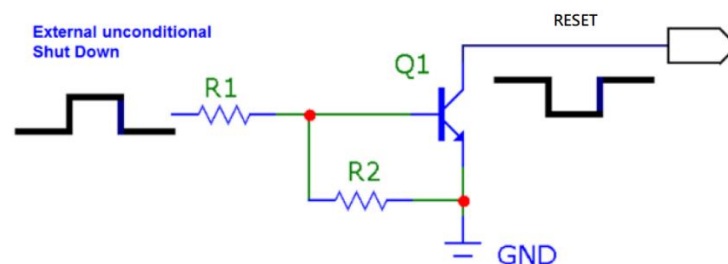


**Note:** THIS SIGNAL IS NOT ACTIVE BY DEFAULT. REFER TO AT#SLED DESCRIPTION IN THE AT COMMAND USER GUIDE.

#### 3.2. RESET

To unconditionally shut down the RYP9000\_Series -mPCIe module, the RESET pad must be tied low for at least 1000 milliseconds and then released.

Figure shows a simple circuit for applying an unconditional shutdown.





**Note:** Recommended values are as follows:  $R2 = 47k\Omega$ ,  $R1 = 10k\Omega$ .



**Note:** Do not use any pull-up resistor on the RESET line or any totem pole digital output. Using a pull-up resistor may cause latch-up problems on the RYP9000\_Series -mPCIe power regulator and improper functioning of the module. The RESET line must be connected only in an open-collector configuration.



**Note:** The Unconditional Hardware Shutdown must always be implemented on the boards, but this function must use it only as an emergency exit procedure, and not as a normal power-off operation. Use the AT#SHDN command instead.

### 3.3. USB Port

The RYP9000\_Series -mPCIe module includes a Universal Serial Bus (USB) transceiver, which operates at USB high-speed (480 Mbits/sec). It can also operate with USB full-speed hosts (12 Mbits/sec).

It is compliant with the USB 2.0 specification and can be used for control and data transfers as well as for diagnostic monitoring and firmware update.

The USB port is typically the main interface between the RYP9000\_Series -mPCIe module and OEM hardware.



**Note:** The USB\_D+ and USB\_D- signals have a clock rate of 480 MHz. The signal traces must be routed carefully. Minimize trace lengths, number of vias, and capacitive loading. The impedance value should be as close as possible to 90 Ohms differential.

Table below lists the USB interface signals:

Signal	Pin	Usage
USB_D-	36	Minus (-) line of the differential, bi-directional USB signal to/from the peripheral device
USB_D+	38	Plus (+) line of the differential, bi-directional USB signal to/from the peripheral device

### 3.4. Serial Port

The serial port is typically a secondary interface between the RYP9000\_Series -mPCIe module and OEM hardware. MODEM SERIAL PORT is available on RYP9000\_Series -mPCIe adaptor

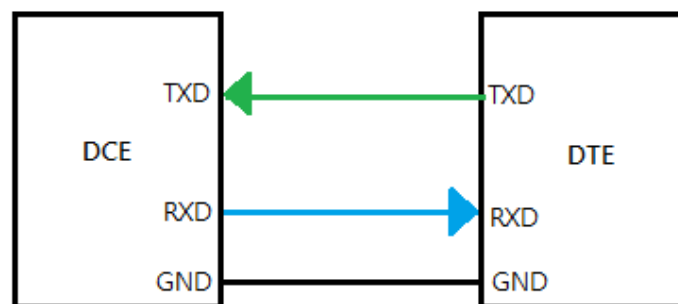
Several configurations can be designed for the serial port on the OEM hardware.

The most common configurations are:

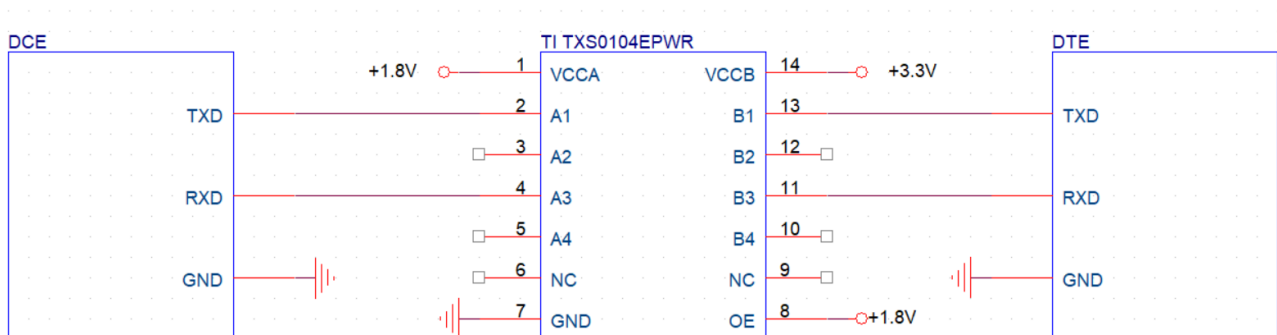
- RS232 PC com port
- Microcontroller UART @ 1.8V (Universal Asynchronous Receive Transmit)
- Microcontroller UART @ 3.3V/5V or other voltages different from 1.8V

Depending on the type of serial port on the OEM hardware, a level translator circuit may be needed to make the system operate. The only configuration that does not need level translation is the 1.8V UART.

Microcontroller UART @ 1.8V application circuit:

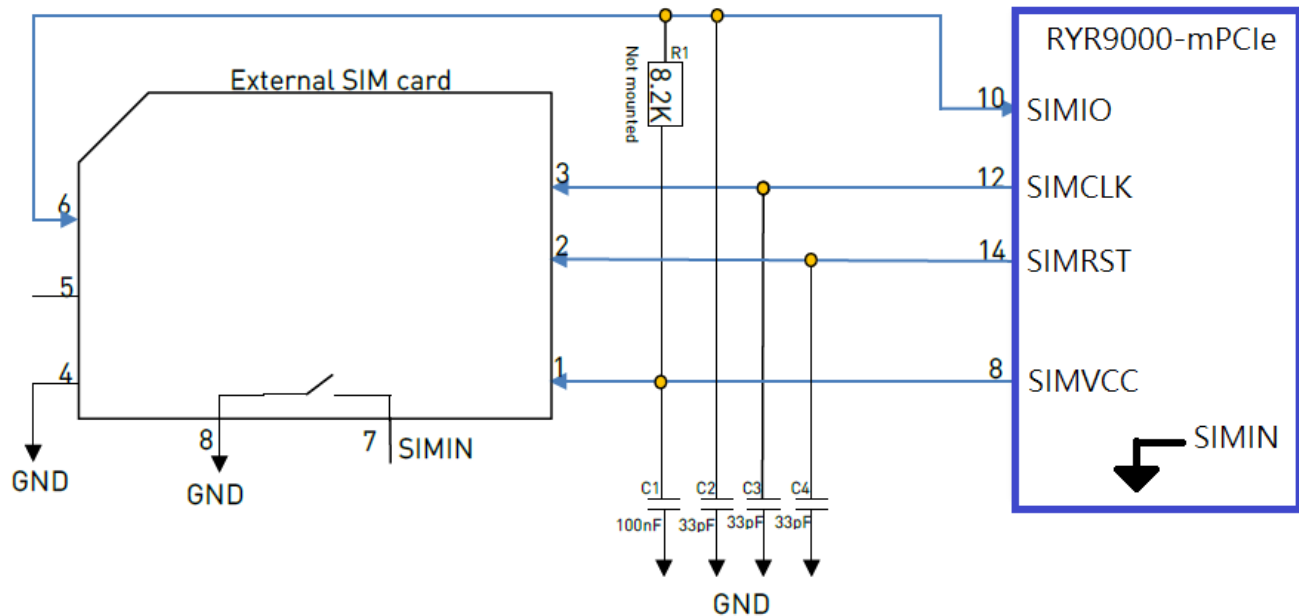


Microcontroller UART @ 3.3V/5V application circuit:



### 3.5. SIM Interface

The SIM pins provide the connections necessary to interface to a SIM socket located on the host device. The Voltage levels over this interface comply with 3GPP standards. SIMIN line terminated to GND internally for standard RZR9000\_Series variant without either SIM holder or onboard eSIM.



**Note:** The resistor value on SIMIO pulled up to SIMVCC should be defined accordingly in order to be compliant with 3GPP specification. RZR9000\_Series - mPCIe contains an internal pull-up resistor on SIMIO. However, the un-mounted option in the application design can be recommended in order to tune R1 if necessary.

## 4. RF SECTION

### 4.1. Band Variants

RYP9000\_Series -mPCIe modules bands combinations are listed below:

Product	2G Band	3G Band	4G Band	Region
RYP91NA	2,3,5,8	1,2,4,5,8	2,4,12	North America
RYP91NS	-	-	2, 4, 5, 12, 25, 26	North America - Sprint
RYP91AP	-	1,5,6,8,19	1, 3, 5, 8, 9, 18, 19, 26,28	Asia-Pacific
RYP91EU	3,8	1,3,8	1, 3, 7, 8, 20, 28A	Europe
RYP91EX	3,8	1,3,8	1, 3, 7, 8, 20, 28A	Europe
RYP91NF	-	2,4,5	2, 4, 5, 12, 13, 14, 66, 71	North America
RYP91LA	2,3,5,8	1,2,4,5	1, 2, 3, 4, 5, 7, 28	Latin America
RYP91WX	2,3,5,8	1,2,4,5,8,19	1, 2, 3, 4, 5, 7, 8, 12, 13, 14, 26,19, 20, 28	Worldwide

### 4.2. Antenna Connectors

The RYP9000\_Series -mPCIe adapter is equipped with a set of 50  $\Omega$  RF U.FL. connectors from Hirose U.FL-R-SMT-1.

The available connectors are:



The presence of all the connectors depends on the product characteristics and the supported functionalities.

For more information about mating connectors, visit the website <https://www.hirose.com/>

The antenna connection is one of the most important aspect in the full product design as it strongly affects the product overall performances, so please read carefully and follow the requirements and the guidelines for a proper design.

The RYP9000\_Series -mPCIe adapter is provided with three RF connectors.

The available connectors are:

- Main RF antenna (ANT)
- RX Diversity Antenna (DIV)
- GNSS Antenna (GPS)

Connecting cables between the module and the antenna must have an impedance of  $50\ \Omega$ .

If the module impedance does not match, the RF performance is reduced significantly.

If the host device is not designed to use the module diversity or the GPS antenna, terminate the interface with a  $50\ \Omega$  load.